BAS20H

High Voltage Switching Diode

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V_R	200	Vdc
Repetitive Peak Reverse Voltage	V_{RRM}	200	Vdc
Continuous Forward Current	l _F	200	mAdc
Peak Forward Surge Current	I _{FM(surge)}	625	mAdc
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)	I _{FRM}	500	mA
Non-Repetitive Peak Forward Current (Square Wave, $T_J = 25^{\circ}C$ prior to surge) $t = 1 \mu s$ t = 1 ms t = 1 s	I _{FSM}	5.0 2.0 0.5	A

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board* T _A = 25°C Derate above 25°C	P _D	200 1.57	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Voltage Leakage Current (V _R = 200 Vdc) (V _R = 200 Vdc, T _J = 150°C)	I _R	-	1.0 100	μAdc
Reverse Breakdown Voltage (I _{BR} = 100 μAdc)	$V_{(BR)}$	250	1	Vdc
Forward Voltage (I _F = 100 mAdc) (I _F = 200 mAdc)	V _F		1000 1250	mV
Diode Capacitance (V _R = 0, f = 1.0 MHz)	C _D	-	5.0	pF
Reverse Recovery Time $(I_F = I_R = 30 \text{ mAdc}, R_L = 100 \Omega)$	t _{rr}	-	50	ns



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HIGH VOLTAGE SWITCHING DIODE





SOD-323 CASE 477 STYLE 1

MARKING DIAGRAM



JR = Specific Device Code

M = Date Code*

■ = Pb-Free Package

(Note: Microdot may be in either location)
*Date Code orientation may vary depending upon manufacturing location.

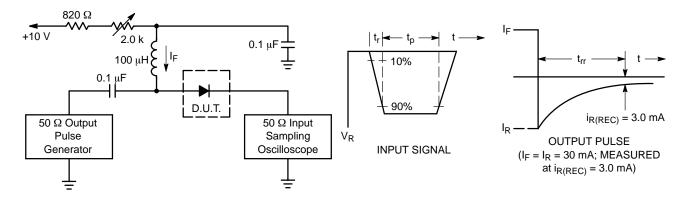
ORDERING INFORMATION

Device	Package	Shipping [†]
BAS20HT1G	SOD-323 (Pb-Free)	3000 / Tape & Reel
SBAS20HT1G	SOD-323 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

^{*}FR-5 Minimum Pad

BAS20H



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 30 mA.

- 2. Input pulse is adjusted so I_{R(peak)} is equal to 30 mA.
- 3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

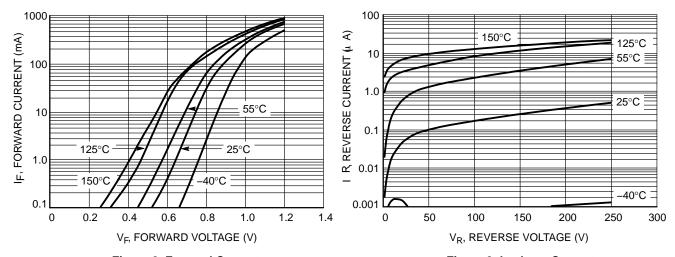


Figure 2. Forward Current

Figure 3. Leakage Current

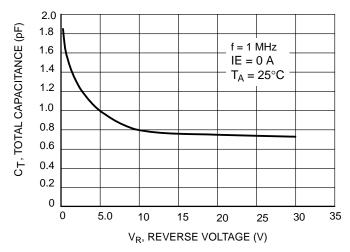
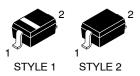


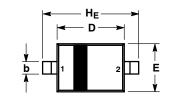
Figure 4. Total Capacitance

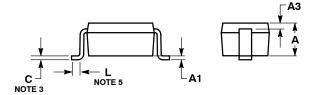


SOD-323 CASE 477-02 **ISSUE H**

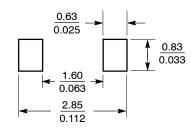
DATE 13 MAR 2007

SCALE 4:1





SOLDERING FOOTPRINT*

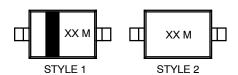


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD
- FLASH, PROTRUSIONS OR GATE BURRS.
 5. DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS				INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.90	1.00	0.031	0.035	0.040	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A3	0.15 REF			0	0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016	
С	0.089	0.12	0.177	0.003	0.005	0.007	
D	1.60	1.70	1.80	0.062	0.066	0.070	
E	1.15	1.25	1.35	0.045	0.049	0.053	
L	0.08			0.003			
HE	2.30	2.50	2.70	0.090	0.098	0.105	

GENERIC MARKING DIAGRAM*



XX = Specific Device Code M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

PIN 1. CATHODE (POLARITY BAND) 2. ANODE

NO POLARITY

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